

# **CLEANING SUBSTRATE FOR CLEANING AND REGENERATING A MOLD**

## ABSTRACT

A cleaning substrate for cleaning and regenerating a mold is disclosed. The  
5 mold is contaminated after repeatedly packaging the semiconductor device by making  
use of thermosetting resin. At least a protrusion of the substrate can substantially  
match with and be contained within the edges of the mold cavity of the mold when the  
cleaning substrate is placed in the mold.